

Title (en)
HOT-MELT ADHESIVE COMPOSITION

Title (de)
SCHMELZKLEBSTOFFZUSAMMENSETZUNG

Title (fr)
COMPOSITION ADHÉSIVE THERMOFUSIBLE

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Application
EP 22801844 A 20221013

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Abstract (en)
[origin: WO2023062324A1] The invention relates to a hot-melt adhesive composition comprising: (i) at least one specific semi-crystalline aliphatic copolyamide; (ii) at least one filler, the carbon atom content of which is between 60 and 100% relative to the number of atoms constituting the filler, the carbonaceous filler having a median particle size D90 ranging from 1 to 400 micrometers; (iii) at least one electrically insulative filler selected from the metal oxides and nitrides, the sum of the contents of the carbonaceous filler and the electrically insulative filler is between 30 and 75% by weight relative to the total weight of the composition, said fillers having a median particle size D90 ranging from 1 to 400 micrometers The invention also relates to the method for preparing same and to the use thereof.

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